

TK16H60C-VB Datasheet

N-Channel 600 V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	600					
R _{DS(on)} at 25 °C (Ω)	$V_{GS} = 10 V$	0.23				
Q _g Typ. (nC)	24					
Q _{gs} (nC)	6					
Q _{gd} (nC)	11					
Configuration	Single					

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)



TO-3P G G D D (TAB) S s N-Channel MOSFET

- **APPLICATIONS**
- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ABSOLUTE MAXIMUM RATINGS (T _C :	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	600	N/	
Gate-Source Voltage			V _{GS}	± 30	V	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	- I _D	15		
	V _{GS} at 10 V	T _C = 100 °C		10	А	
Pulsed Drain Current ^a			I _{DM}	45		
Linear Derating Factor				1.4	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	286	mJ	
Maximum Power Dissipation			PD	180	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 125 °C		-l\ / / -lt	37		
Reverse Diode dV/dt ^d			dV/dt	23	V/ns	
Soldering Recommendations (Peak Temperature) ^c	for 10 s			300	°C	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD} = 50$ V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.5 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C.



THERMAL RESISTANCE RATI	NGS								
PARAMETER	SYMBOL	TYP. MAX.			UNIT				
Maximum Junction-to-Ambient	R _{thJA}	- 62							
Maximum Junction-to-Case (Drain)	R _{thJC}	- 0.7				°C/W			
SPECIFICATIONS (T _J = 25 $^{\circ}$ C, u	inless otherwi	se noted)							
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT	
Static	<u>.</u>	•			•		•	•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D =	250 µA	600	-	-		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		I _D = 1 mA	-	0.75	-	V/°C	
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	2	-	4	V	
		$V_{GS} = \pm 20 V$ $V_{GS} = \pm 30 V$		-	-	± 100	nA		
Gate-Source Leakage	I _{GSS}			-	-	± 1	μA		
		$V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 000 \text{ V}$		-	-	1	<u> </u>		
Zero Gate Voltage Drain Current	I _{DSS}		$V_{DS} = 520 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			-	10	μA	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V		$I_D = 8 A$	-	0.23	-	Ω	
Forward Transconductance		V _{DS}	= 30 V, I _D	= 8 A	-	5.6	-	S	
Dynamic					1	1	1		
Input Capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz		-	1640	-	pF		
Output Capacitance	C _{oss}			-	80	-			
Reverse Transfer Capacitance	C _{rss}			-	4	-			
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	$V_{DS} = 0 V $ to 520 V, $V_{GS} = 0 V$		-	63	-			
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	213	-			
Total Gate Charge	Qg				-	24	48		
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$ $I_D = 8 J$		A, V _{DS} = 520 V	-	6	-	nC	
Gate-Drain Charge	Q _{gd}				-	11	-		
Turn-On Delay Time	t _{d(on)}	V_{DD} = 520V, I $_D$ = 8 A, V_{GS} = 10 V, R_g = 9.1 Ω		-	18	36	- ns		
Rise Time	t _r			-	24	48			
Turn-Off Delay Time	t _{d(off)}			-	48	96			
Fall Time	t _f			-	25	50			
Gate Input Resistance	Rg	f = 1 MHz, open drain		-	0.8	-	Ω		
Drain-Source Body Diode Characteristi	cs	T			1			1	
Continuous Source-Drain Diode Current	ا _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	A		
Pulsed Diode Forward Current	I _{SM}			-	-	38			
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 8 A, V _{GS} = 0 V		-	-	1.2	V		
Reverse Recovery Time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 8 \text{ A},$ dl/dt = 100 A/µs, V _R = 400 V		-	325	-	ns		
Reverse Recovery Charge	Q _{rr}			-	4.6	-	μC		
Reverse Recovery Current	I _{RRM}			<u> </u>	20				

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

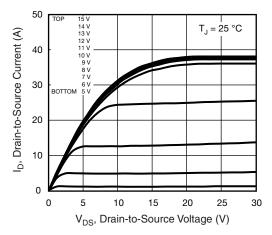


Fig. 1 - Typical Output Characteristics

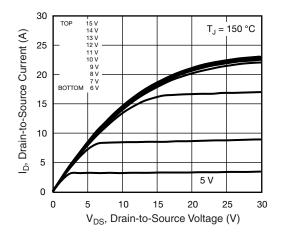


Fig. 2 - Typical Output Characteristics

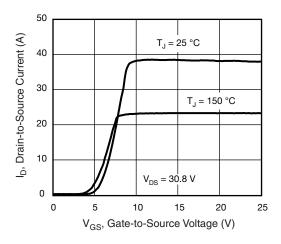


Fig. 3 - Typical Transfer Characteristics

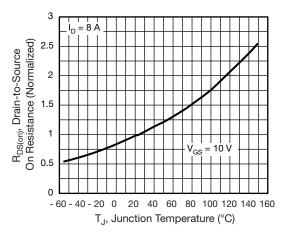


Fig. 4 - Normalized On-Resistance vs. Temperature

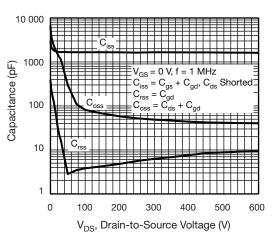


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

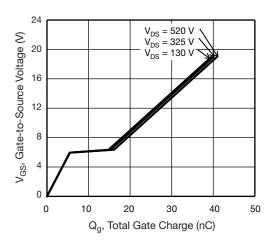


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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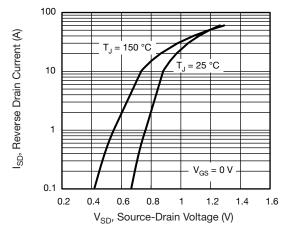


Fig. 7 - Typical Source-Drain Diode Forward Voltage

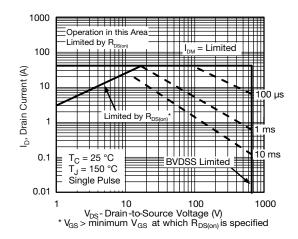


Fig. 8 - Maximum Safe Operating Area

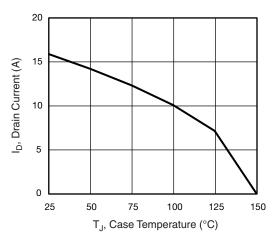


Fig. 9 - Maximum Drain Current vs. Case Temperature

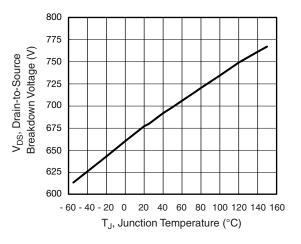


Fig. 10 - Temperature vs. Drain-to-Source Voltage

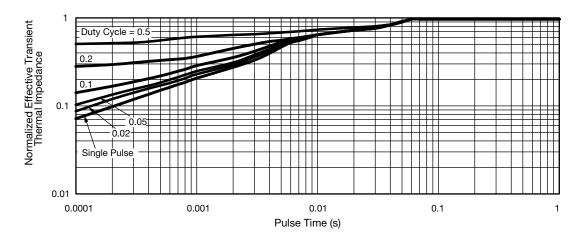


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



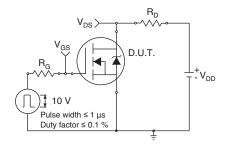


Fig. 12 - Switching Time Test Circuit

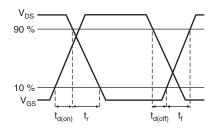


Fig. 13 - Switching Time Waveforms

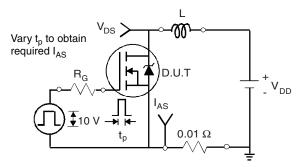


Fig. 14 - Unclamped Inductive Test Circuit

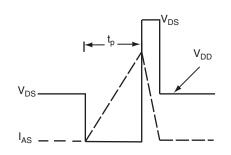


Fig. 15 - Unclamped Inductive Waveforms

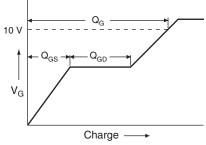


Fig. 16 - Basic Gate Charge Waveform

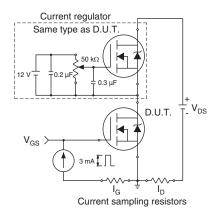
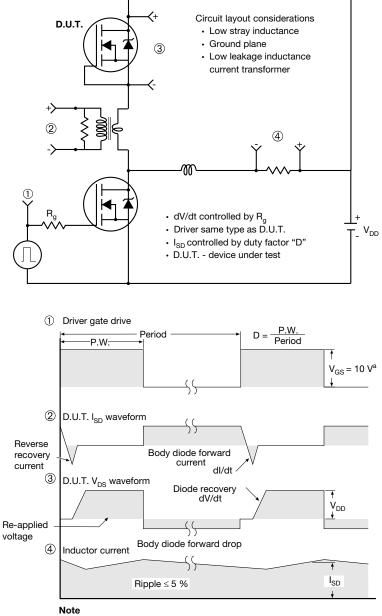


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit

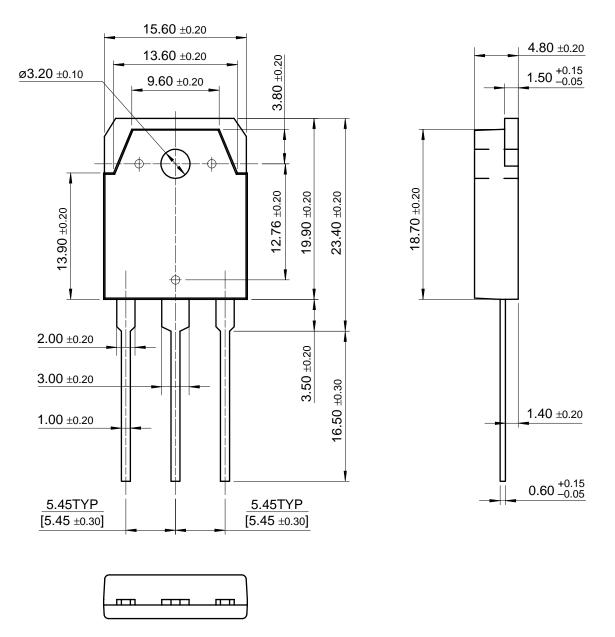


a. $V_{GS} = 5$ V for logic level devices

Fig. 18 - For N-Channel



TO-3P





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